Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service – S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity $\,$ indicator card on top side

PLEASE CLICK HERE FOR MORE INFORMATION []High Frequency PCB wholesales china

Product Description

PCB P/N	LC057-V1
Layer Count	1L
Material	Base Ceramics
Board thk	1.6mm
copper thk	11oz
Smallest hole size	/
No. of holes (pcs)	/
line w/s	15mil
Impedance control. Y / N (Tol %)	Ν
Surface Finishing	ENIG(Au:0.05um)
Solder Mask Silkscreen	White / N/A
Single board size	Dim X (mm):89;Dim Y (mm):175
Panelisation	Dim X (mm):89;Dim Y (mm):175;No Of UPS:1
Special	N
Routing/Punching	CNC

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Halogen Free PCB manufacturer china

FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

1. The process is strictly controlled under ISO 9001:2008 standards.

2.Extensive use of software in managing the production process

3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).

4.Dedicated quality assurance team with failure case analysis process

5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting \rightarrow Inner dry film \rightarrow inner etching \rightarrow Inner AOI \rightarrow Multi-bond \rightarrow Layer stack up Pressing \rightarrow Drilling \rightarrow PTH \rightarrow Panel Plating \rightarrow Outer Dry Film \rightarrow Pattern Plating \rightarrow Outer etching \rightarrow Outer AOI \rightarrow Solder Mask \rightarrow Component Mark \rightarrow Surface finish \rightarrow Routing \rightarrow E/T \rightarrow Visual Inspection.

Our Team



Factory PCB





Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

- Factory SMT











Certifications





O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

Test Report

SGS

Test Report

No. SZXEC1900530401

Date: 30 Mar 2019 Page 2 of 6

Test Part Description :

Test Results :

Specimen No. SGS Sample ID Description SN1 SZX19-005304.001 Green"PCB"

Date: 30 Mar 2019 Page 1 of 6

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

No. SZXEC1900530401

SGS Job No. :	RP19-005089 - SZ
Date of Sample Received :	22 Mar 2019
Testing Period :	22 Mar 2019 - 30 Mar 2019
Test Requested :	Selected test(s) as requested by client.
Test Method :	Please refer to next page(s).
Test Results :	Please refer to next page(s).
Conclusion :	Based on the performed tests on submitted sample(s), the results of Lead. Marcury, Cadmium, Horavalent chromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Big2-ethylhexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dbutyl phthalate (DBP), and Disobutyl phthalate (DBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU.

1313.FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

Tina

Tina Fan Approved Signatory



Member of the SGS Group (SGS SA)

Remarks : (1) 1 mg/kg = 1 ppm = 0.0001%
(2) MDL = Method Detection Limit (3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC 62321-5:2013, IEC 62321-7:2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
_ead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1.000	mg/kg		ND
Monobromobiphenyl		mg/kg	5	ND
Dibromobiphenyl	12	mg/kg	5	ND
Tribromobiphenyl		mg/kg	5	ND
Tetrabromobiphenyl		mg/kg	5	ND
Pentabromobiphenyl		mg/kg	5	ND
Hexabromobiphenyl		mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl		mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl		mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg		ND
Monobromodiphenyl ether		mg/kg	5	ND
Dibromodiphen yl ether		mg/kg	5	ND
Tribromodiphenyl ether		mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



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UL Product iQ™



E490354

ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN (HK) CO LTD

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

	Cond	Width			Max			Max			
		Min	Cond	SS/	Area	Solo	der	Oper		Meets	с
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	UL796	т
Туре	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	с	sec	с	Class	DSR	L
Multilayer (m	ass laminate) p	rinted wiring l	ooards.								
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	nted wiring bo	ards.	A.,								
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	rinted wiring b	oards.	n.					600	3 7	200	
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0		-
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	-
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ		*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

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Packaging & Delivery

Shipping service





Quick Turn Lead Time					
Layer Count:	Lead Tim	Special Requirement			
1L/2L	2-3days	24 Hours,48 Hours			
4L	3-4days	48 Hours			
6L	4-5days	72 Hours			
8L	5-6days	NA			
10L	6-7days	NA			
12L	7-8days	NA			
14L	8-9days	NA			

	Standard Lead Time					
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

Process Capability

PCB Production Capabilities

Layer Count: 1Layer-32Layer Finished copper thickness[] 1/3oz-12oz Min Line width/spacing internal[] 3.0mil/3.0mil Min Line width/spacing external: 4.0mil/4.0mil Max Aspect Ratio: 10:1 Board thickness[] 0.2mm-5.0mm Max Panel size(inches): 635*1500mm Minimum Drilled Hole Size: 4mil Plated Hole Tolerance: +/-3mil Blind/Buried Vias (All Types): YES Via Fill(Conductive,Non-Conductive): YES Base Material: FR-4,FR-4high Tg.Halogen free material,Rogers,Aluminium base,Polyimide, Heavy Copper Surface finishes: HASL,OSP,ENIG,HAL-LF,Immersion silver,Immersion Tin,Gold fingers,Carbon ink

SMT Production Capabilities

PCB Material: FR-4,CEM-1,CEM-3,Aluminum-based board Max PCB size: 510x460mm Min PCB size[]50x50mm PCB Thickness[]0.5mm-4.5mm Board thickness[]0.5-4mm Min Components size: 0201 Standard chip size component: 0603 and larger Component max height[]15mm Min lead pitch: 0.3mm Min BGA ball pitch:0.4mm Placement precision: +/-0.03mm